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Vishay Siliconix

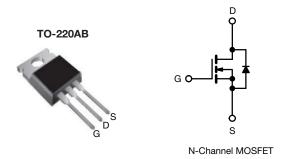
RoHS

COMPLIANT HALOGEN

FREE

EF Series Power MOSFET with Fast Body Diode

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	650)
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.123
Q _g (Max.) (nC)	120)
Q _{gs} (nC)	Q _{gs} (nC) 17	
Q _{gd} (nC)	33	
Configuration	Sing	le



FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High intensity discharge (HID)
 - Light emitting diodes (LEDs)
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- · Renewable energy
 - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
 - LLC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and Halogen-free	SiHP28N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (TC:	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600	V	
Gate-Source Voltage			V_{GS}	± 30	V	
Continuous Drain Current (T _{.I} = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$,	28		
Continuous Drain Current (1) = 150 °C)	V _{GS} at 10 V	T _C = 100 °C	Ι _D	18	A	
Pulsed Drain Current ^a			I _{DM}	75]	
Linear Derating Factor				2	W/°C	
Single Pulse Avalanche Energy b		E _{AS}	691	mJ		
Maximum Power Dissipation			P _D	250	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		-11//-14	70	\//m =	
Reverse Diode dV/dt ^d			dV/dt	50	- V/ns	
Soldering Recommendations (Peak Temperature) c	oldering Recommendations (Peak Temperature) c for 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 7 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 900 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.5	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		•			•	l .	
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} :	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.76	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
0.1.0		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
Zava Cata Valtaga Dvain Curvant		V _{DS} = 480 V, V _{GS} = 0 V		1	μΑ		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	2	mA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 14 A	-	0.107	0.123	Ω
Forward Transconductance	9 _{fs}	V_{DS}	= 30 V, I _D = 14 A	-	9.7	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V,		-	2714	-	
Output Capacitance	C _{oss}		$V_{DS} = 100 V,$	_	123	_	1
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	6	-	pF
Effective output capacitance, energy related ^a	C _{o(er)}	V _{GS} = 0 V, V _{DS} = 0 V to 480 V		-	98	-	Pir
Effective output capacitance, time related b	C _{o(tr)}			-	356	-	1
Total Gate Charge	Qg			-	80	120	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$	$I_D = 14 A, V_{DS} = 480 V$	-	17	-	nC
Gate-Drain Charge	Q _{gd}			-	33	-	
Turn-On Delay Time	t _{d(on)}			-	24	48	
Rise Time	t _r	$V_{DD} = 480 \text{ V}, I_{D} = 14 \text{ A}$ $R_{g} = 9.1 \Omega, V_{GS} = 10 \text{ V}$		-	40	80	1
Turn-Off Delay Time	t _{d(off)}			-	82	123	ns
Fall Time	t _f			-	39	78]
Gate Input Resistance	R _g	f = 1 MHz, open drain		0.2	0.5	1.0	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the		-	-	28	_
Pulsed Diode Forward Current	I _{SM}	integral revers p - n junction	<u> </u>	-	-	70	A
Diode Forward Voltage	V_{SD}	T _J = 25 °C	C, I _S = 11 A, V _{GS} = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	_		-	142	284	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25$ °C, $I_F = I_S = 14$ A, $dI/dt = 100$ A/ μ s, $V_R = 400$ V		-	0.97	1.94	μC
Reverse Recovery Current	I _{RRM}			-	13.2	-	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

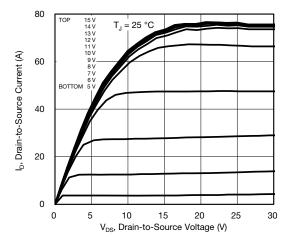


Fig. 1 - Typical Output Characteristics

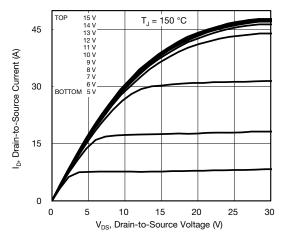


Fig. 2 - Typical Output Characteristics

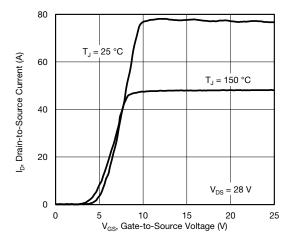


Fig. 3 - Typical Transfer Characteristics

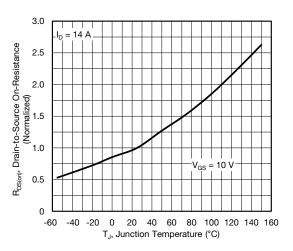


Fig. 4 - Normalized On-Resistance vs. Temperature

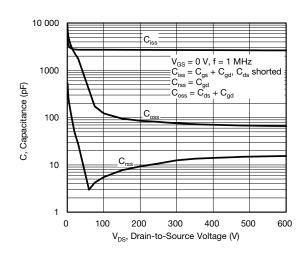


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

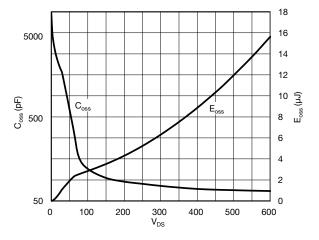


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



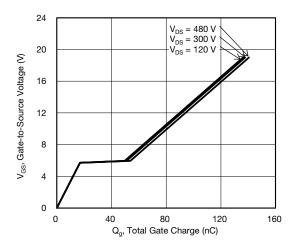


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

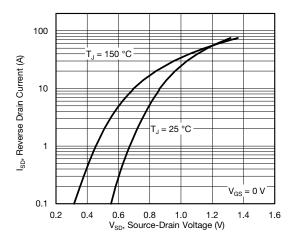


Fig. 8 - Typical Source-Drain Diode Forward Voltage

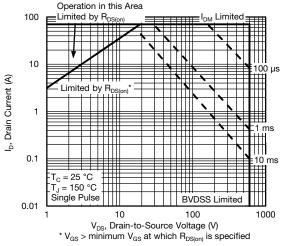


Fig. 9 - Maximum Safe Operating Area

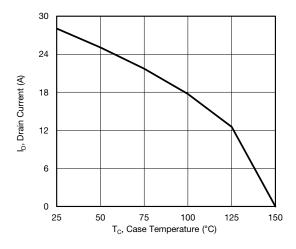


Fig. 10 - Maximum Drain Current vs. Case Temperature

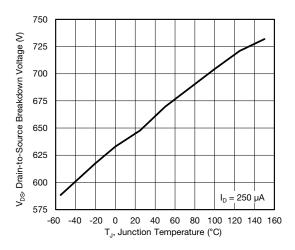


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



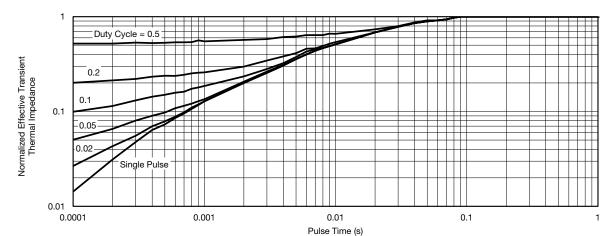


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

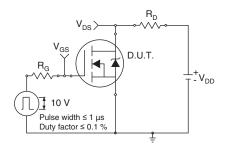


Fig. 13 - Switching Time Test Circuit

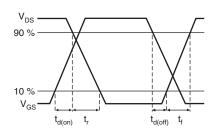


Fig. 14 - Switching Time Waveforms

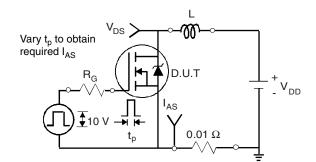


Fig. 15 - Unclamped Inductive Test Circuit

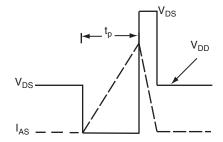


Fig. 16 - Unclamped Inductive Waveforms

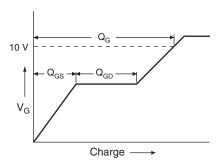


Fig. 17 - Basic Gate Charge Waveform

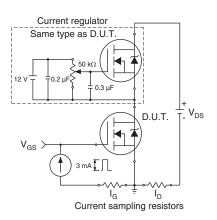
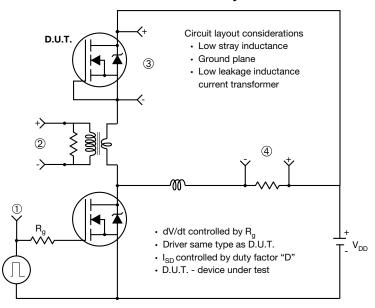


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



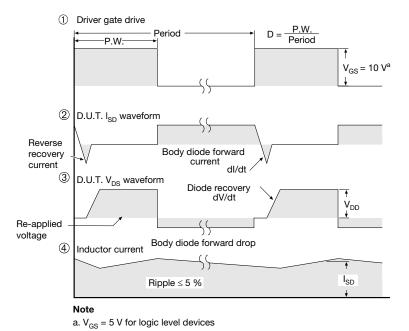
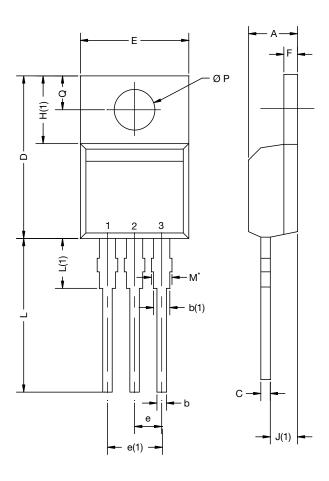


Fig. 19 - For N-Channel

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TO-220-1



DIM.	MILLIM	METERS	INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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